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Vishay Siliconix

N-Channel 30 V (D-S) MOSFET



Marking code: BX

PRODUCT SUMMARY				
V _{DS} (V)	30			
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0192			
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0245			
Q _g typ. (nC)	4.7			
I _D (A)	6 ^d			
Configuration	Single			

FEATURES

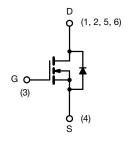
- TrenchFET® Gen IV power MOSFET
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



FREE

APPLICATIONS

- Load Switch
- HDD



N-Channel MOSFET

ORDERING INFORMATION	
Package	TSOP-6
Lead (Pb)-free and halogen-free	Si3410BDV-T1-GE3

ABSOLUTE MAXIMUM RATING	(. _A 20 0, a			LINUT	
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	30	V	
Gate-source voltage		V_{GS}	+20 / -16		
	T _C = 25 °C		6		
0 " 150.00"	T _C = 70 °C	1	6		
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	6 ^{a,b}		
	T _A = 70 °C	†	6 ^{a,b}	Α	
Pulsed drain current		I _{DM}	24		
Continuous source-drain diode current	T _C = 25 °C		2.7		
	T _A = 25 °C	l _S	1.7 ^{a,b}		
Maximum power dissipation	T _C = 25 °C		3.3		
	T _C = 70 °C		2.1	w	
	T _A = 25 °C	P _D	2 ^{a,b}	VV	
	T _A = 70 °C		1.3 ^{a,b}		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature)		_	260		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient a,c	t ≤ 5 s	R _{thJA}	53	62.5	°C/W	
Maximum junction-to-foot (drain)	Steady state	R_{thJF}	32	38	C/VV	

Notes

- a. Surface Mounted on 1" x 1" FR4 board
- b t = 5 s
- c. Maximum under steady state conditions is 110 °C/W
- d. Based on TC = 25 °C

S25-1703-Rev. A, 22-Dec-2025

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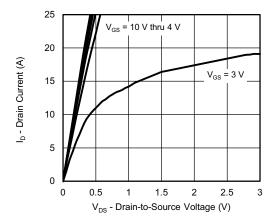
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static						•	
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$		-	14.3	-	mV/°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$	-	-4.7	-		
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2	-	2.2	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = +20 / -16 \text{ V}$	-	-	100	nA	
Zero gate voltage drain current		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μА	
	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	-	-	10		
On-state drain current ^a	I _{D(ON)}	VDS ≥ 5 V, VGS = 10 V	5			Α	
Drain-source on-state resistance ^a	Б	V _{GS} = 10 V, I _D = 5 A	-	0.0155	0.0192	Ω	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$	-	0.0190	0.0245		
Forward transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5 A	-	22	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	765	-	pF	
Output capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	225	-		
Reverse transfer capacitance	C _{rss}		-	14	-		
Catal gata sharas		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 5 A	-	10	15	nC	
Total gate charge	Q_g	V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 5 A	-	4.7	7.1		
Gate-source charge	Q _{gs}		-	2.2	-		
Gate-drain charge	Q_{gd}		-	0.65	-		
Gate resistance	R_g	f = 1 MHz	1.3	6.3	12.6	Ω	
Turn-on delay time	t _{d(on)}		-	6	15		
Rise time	t _r	$V_{DD} = 15 \text{ V}, R_L = 3 \Omega, I_D \cong 5 \text{ A},$	-	25	50		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		15	30		
Fall time	t _f		-	10	20		
Turn-on delay time	t _{d(on)}		-	17	35	ns	
Rise time	t _r	$V_{DD} = 15 \text{ V}, \text{ R}_L = 3 \Omega, \text{ I}_D \cong 5 \text{ A}, \\ V_{GEN} = 4.5 \text{ V}, \text{ R}_g = 1 \Omega \qquad \qquad -$		45	90	1	
Turn-off delay time	t _{d(off)}		-	16	30		
Fall time	t _f		-	27	50		
Drain-Source Body Diode Characterist	cs						
Continuous source-drain diode current	Is	T _C = 25 °C -	-	-	2.7	^	
Pulse diode forward current	I _{SM}		-	-	24	A	
Body diode voltage	V_{SD}	$I_S = 2.7 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.81	1.1	V	
Body diode reverse recovery time	t _{rr}		-	21	40	ns	
Body diode reverse recovery charge	Q _{rr}	L E A di/d+ 100 A/vo T 05 °C	-	10	20	nC	
Reverse recovery fall time	ta	$I_F = 5 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$	-	12	-	r.	
Reverse recovery rise time	t _b		-	9		ns	

Notes

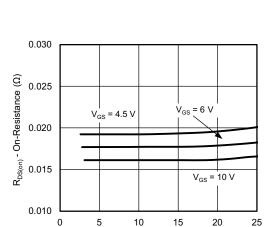
- a. Pulse test: pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



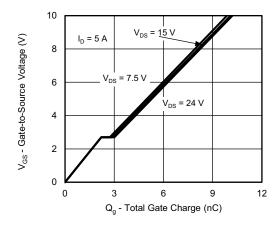


Output Characteristics



On-Resistance vs. Drain Current and Gate Voltage

I_D - Drain Current (A)



Gate Charge

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T_C = 125 °C

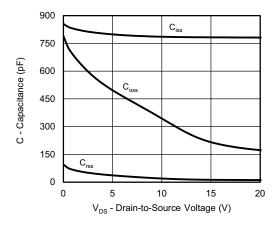
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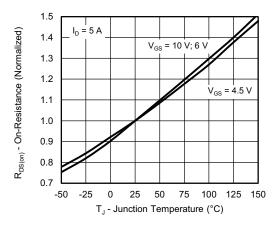
Transfer Characteristics

V_{GS} - Gate-to-Source Voltage (V)

T_C = -55 °C

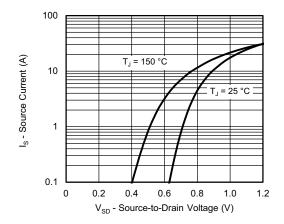


Capacitance

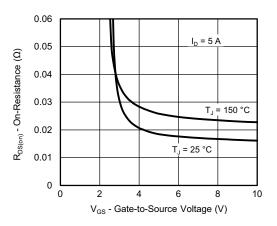


On-Resistance vs. Junction Temperature

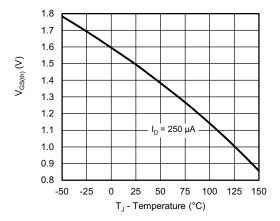




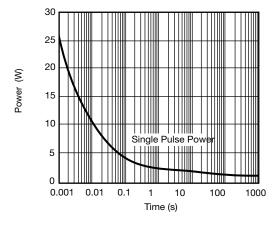
Source-Drain Diode Forward Voltage



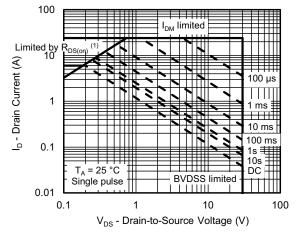
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient





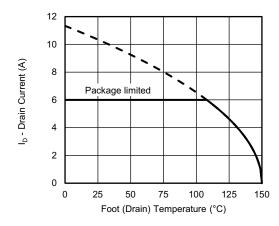
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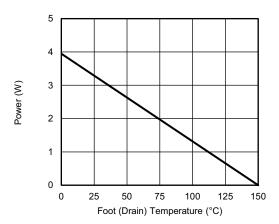
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Note

c. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified







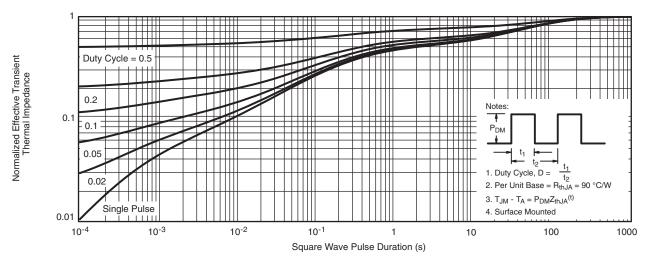
Current Derating a

Power Derating

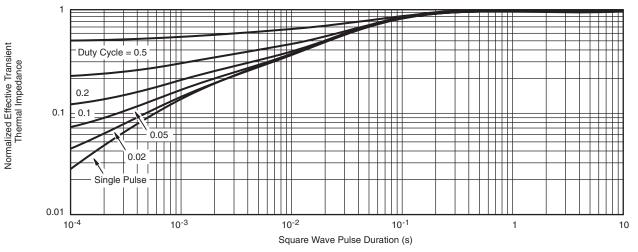
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-foot thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon





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Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg261806.



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